

MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

Inventor: Yamanaka Hideo

Docket No. 075834.00466

Robert J. Depke, Holland & Knight, LLC - (312) 263-3600

FIG. 1

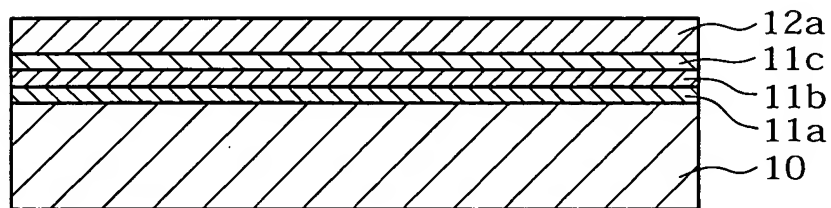
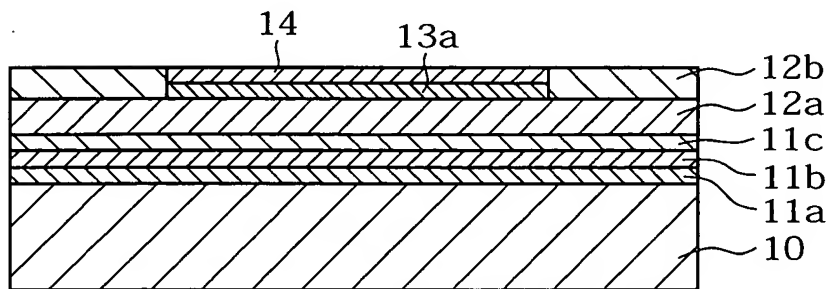
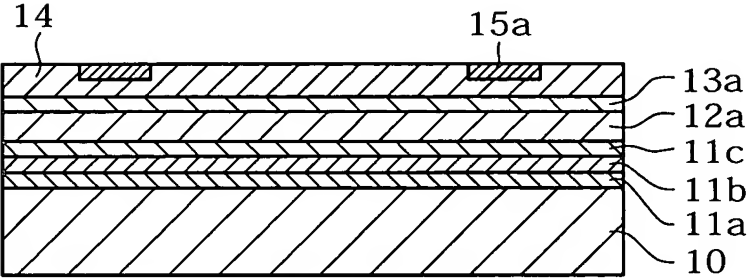


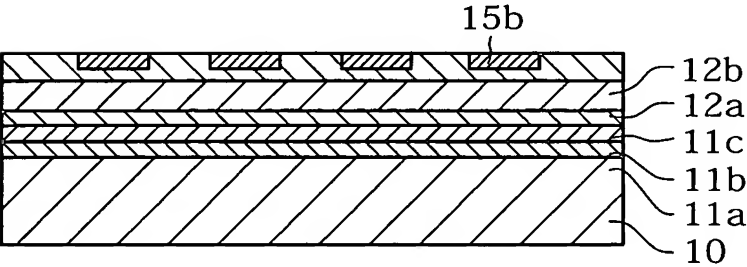
FIG. 2



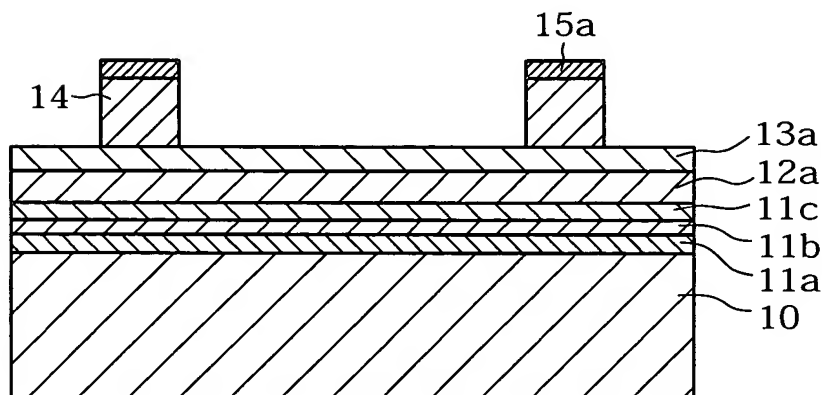
F I G . 3 A



F I G . 3 B



F I G . 4



F I G . 5

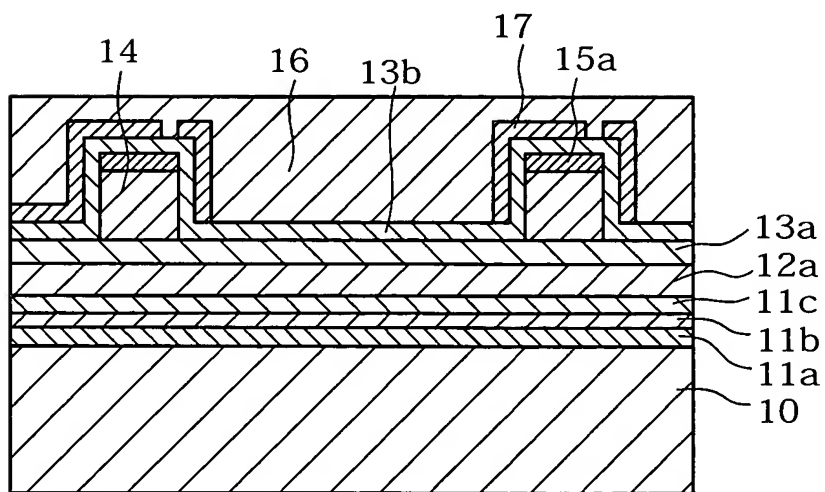
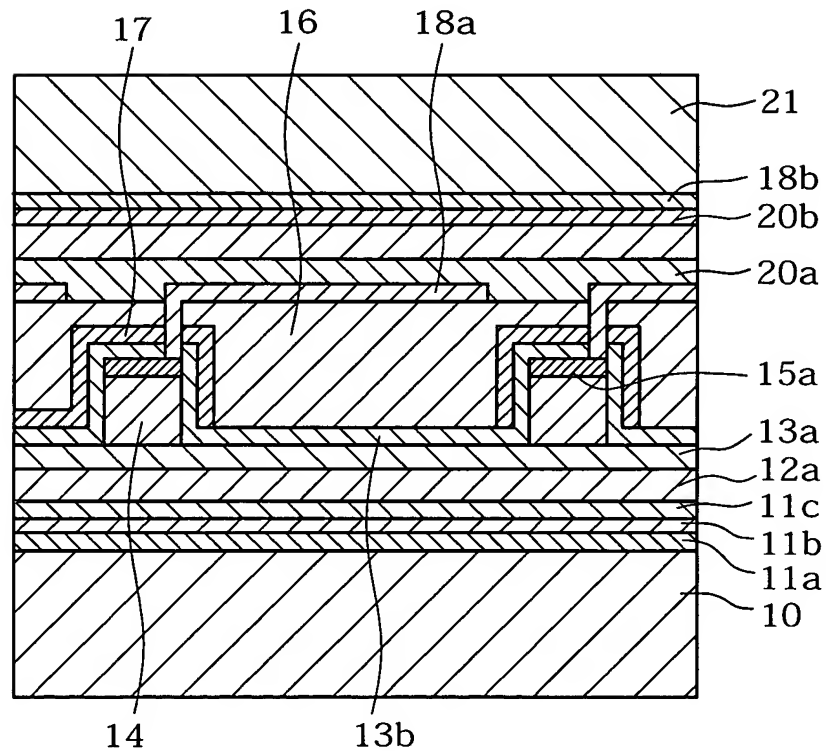
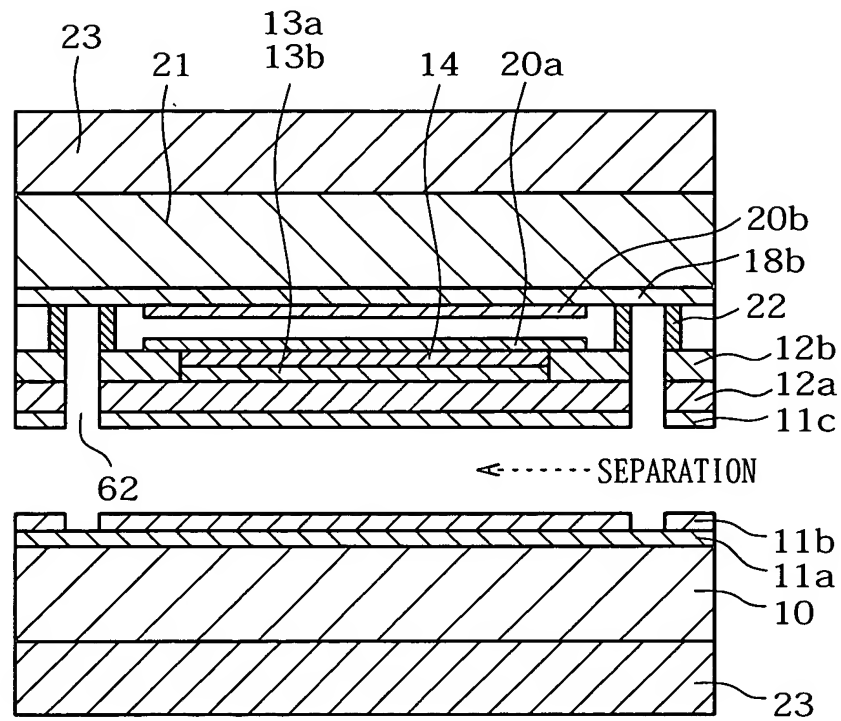


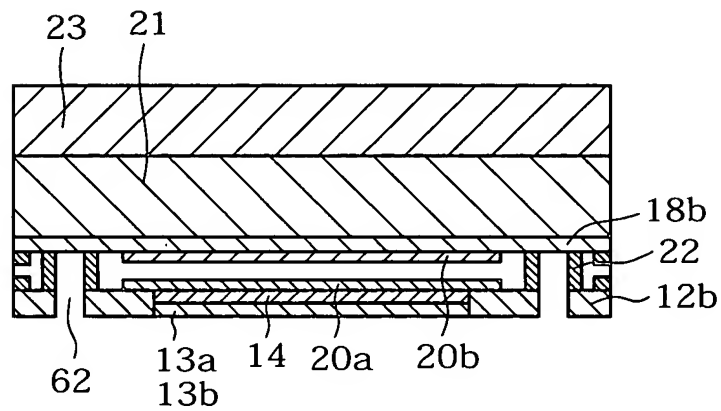
FIG. 6



F I G . 7



F I G . 8 A



F I G . 8 B

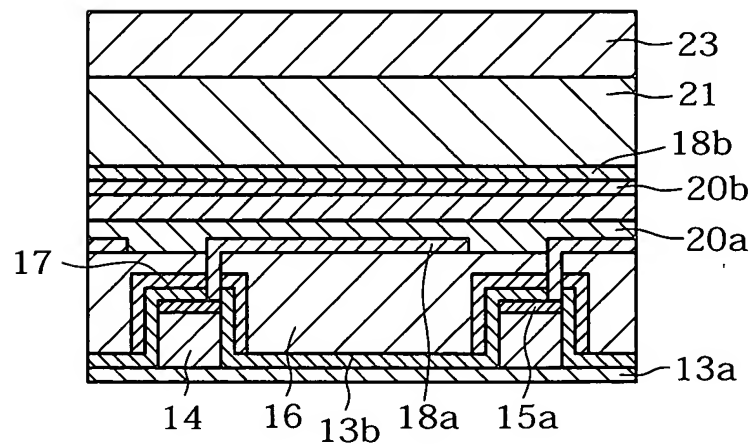


FIG. 9A

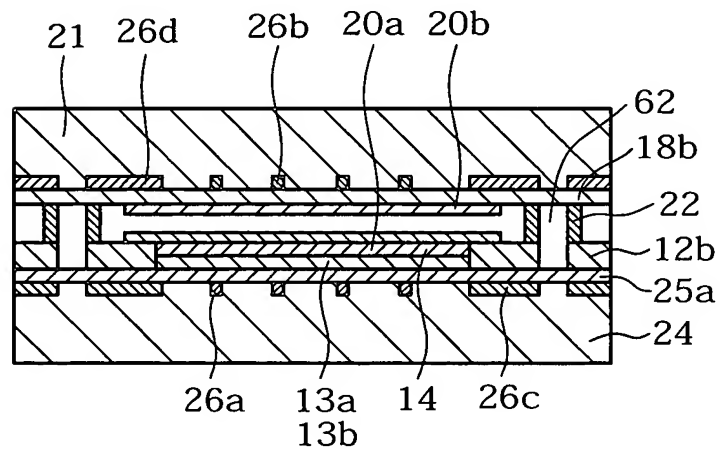


FIG. 9B

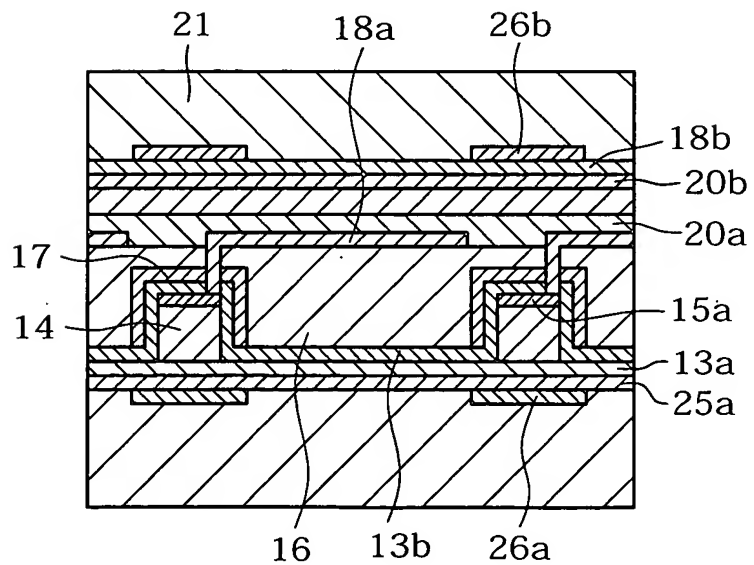


FIG. 10A

(a) WITHOUT A LIGHT-SHIELDING FILM

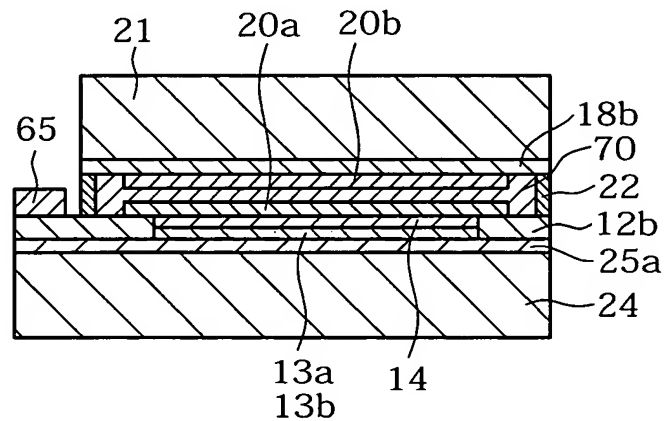
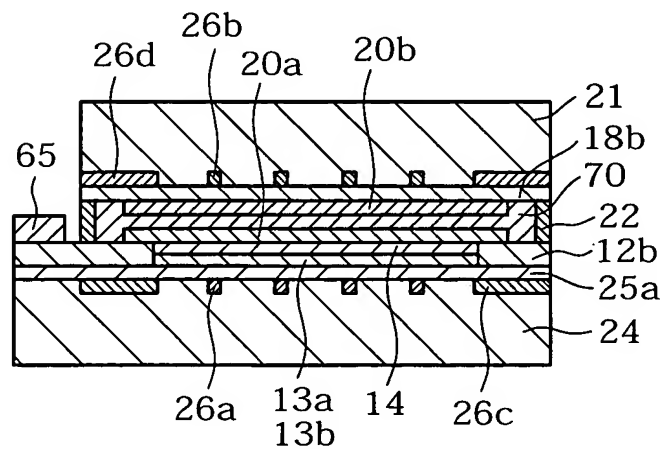
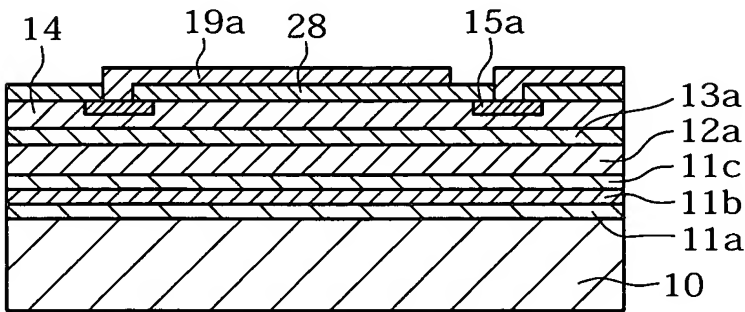


FIG. 10B

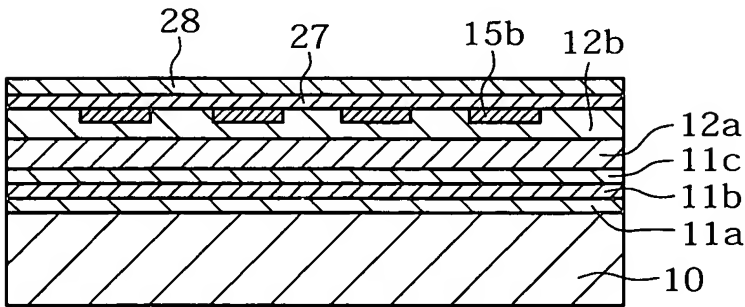
(a) WITH A LIGHT-SHIELDING FILM



F I G. 1 1 A



F I G. 1 1 B



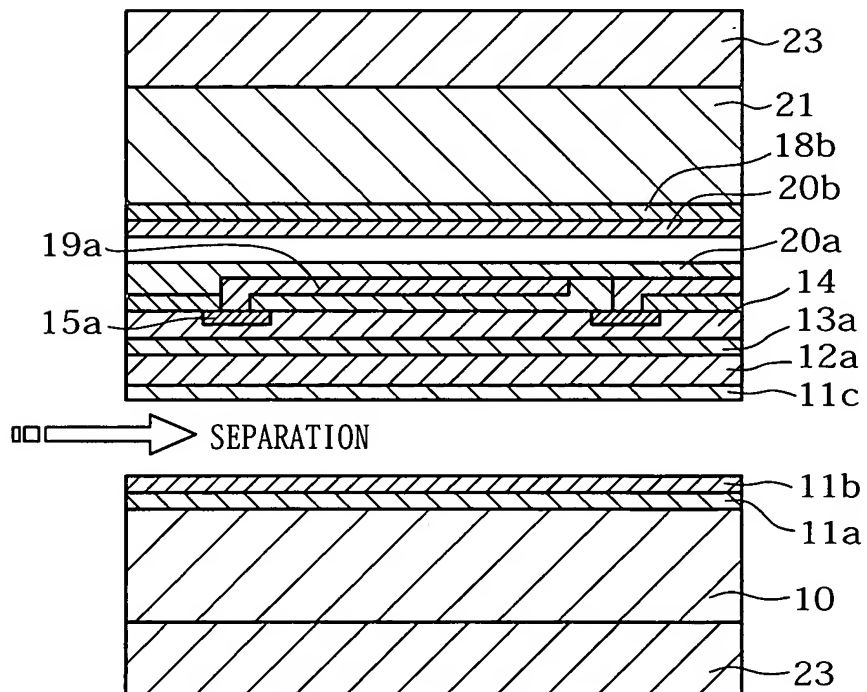


FIG. 13A

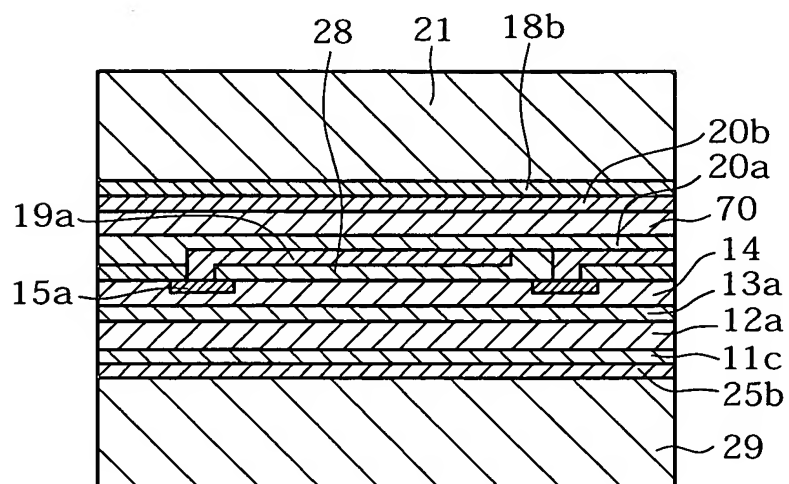
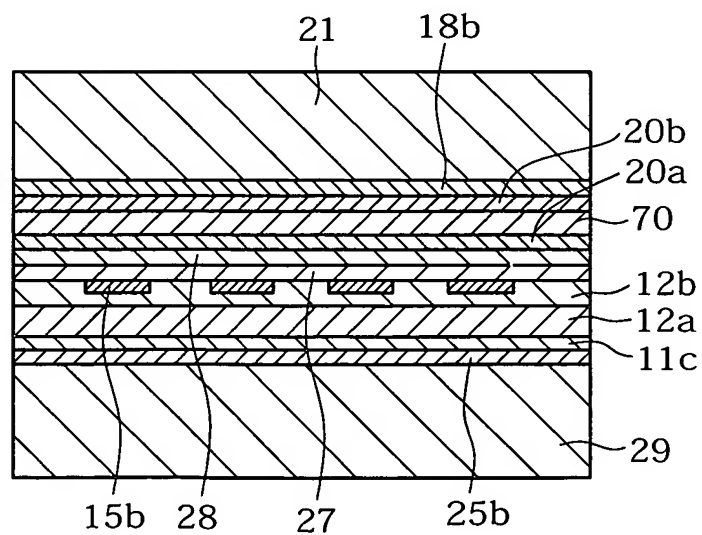


FIG. 13B



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FIG. 14 A

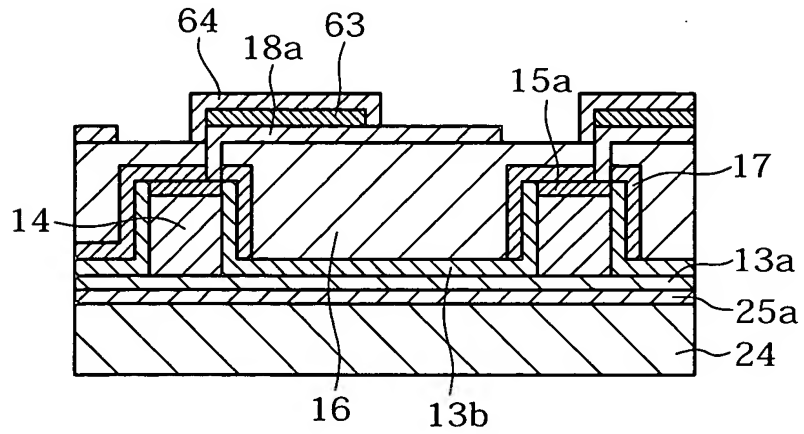
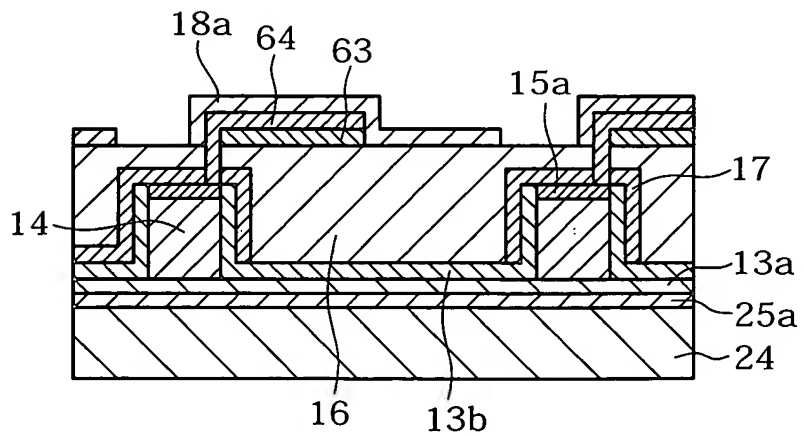
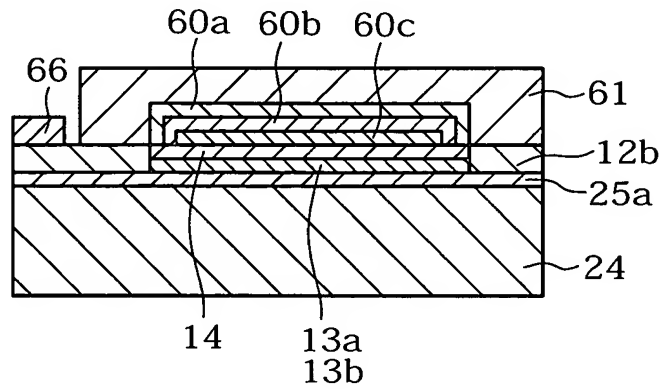


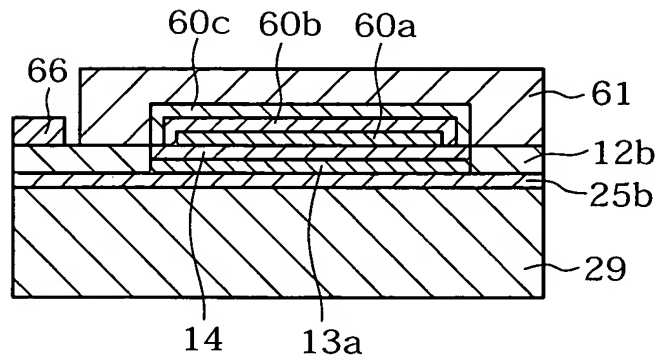
FIG. 14 B



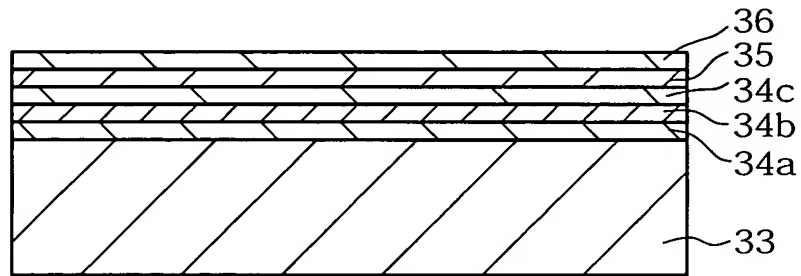
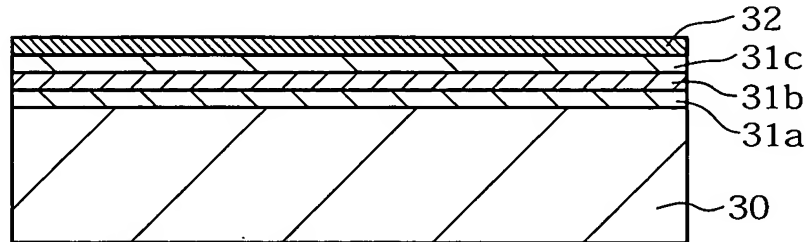
F I G. 1 5



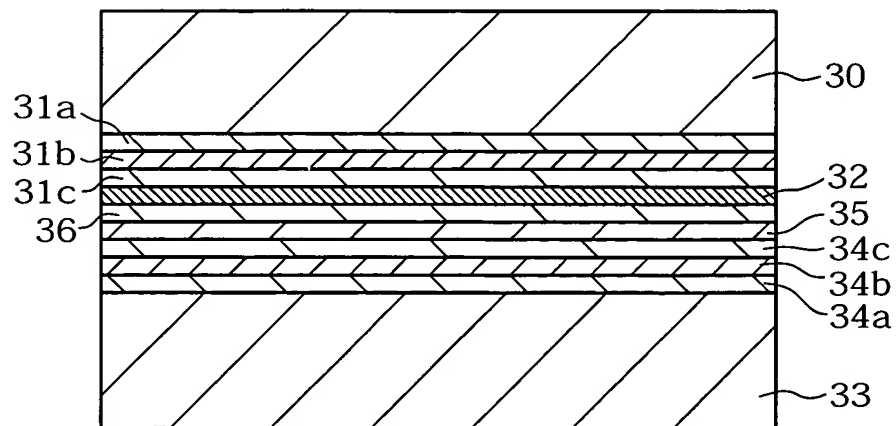
F I G. 1 6



F I G . 1 7



F I G . 1 8



F I G . 1 9

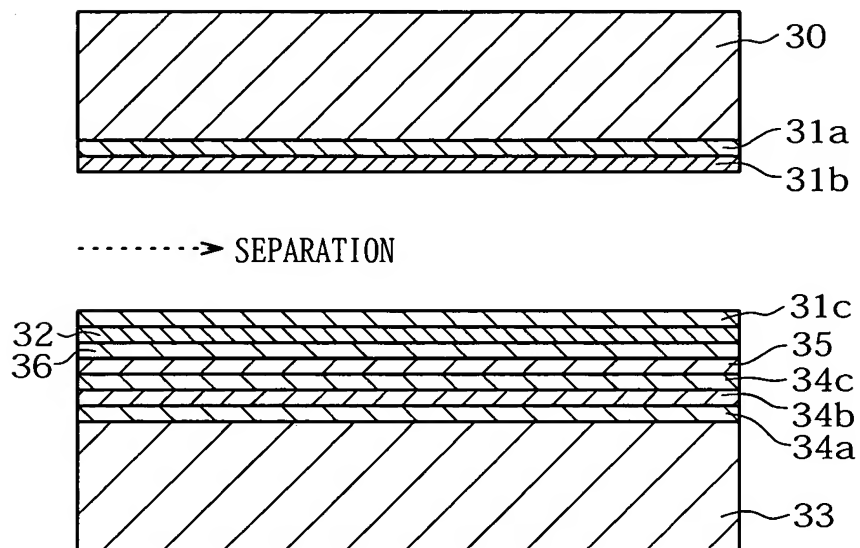


FIG. 20A

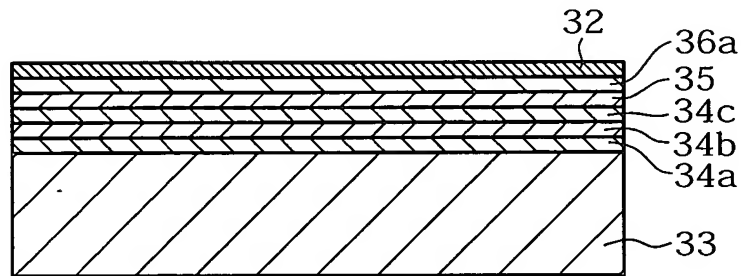
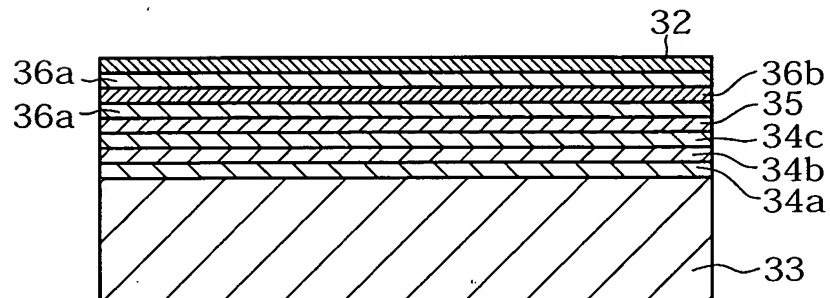
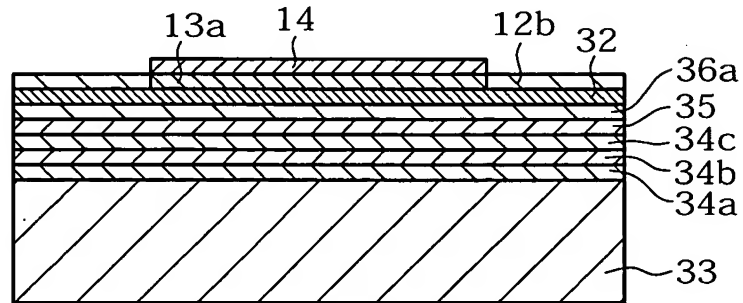


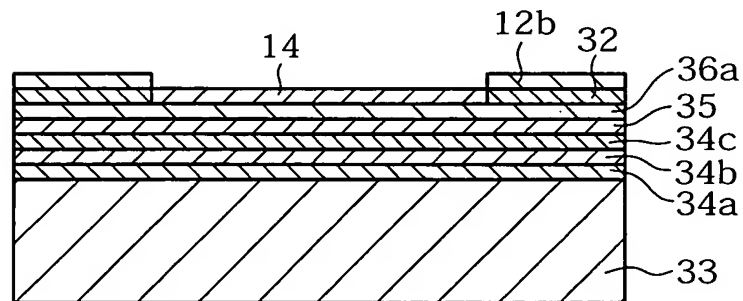
FIG. 20B



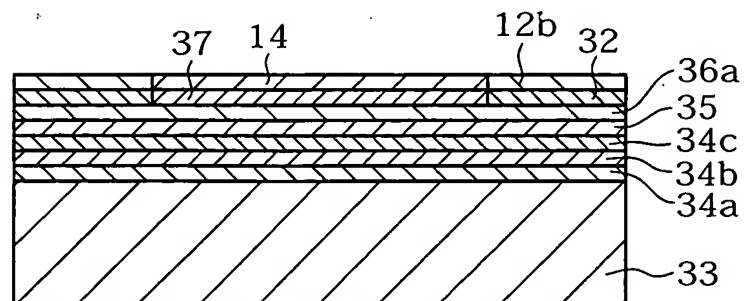
F I G . 2 1 A



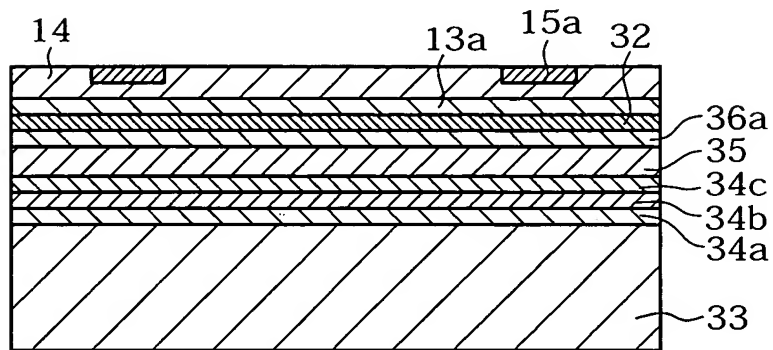
F I G . 2 1 B



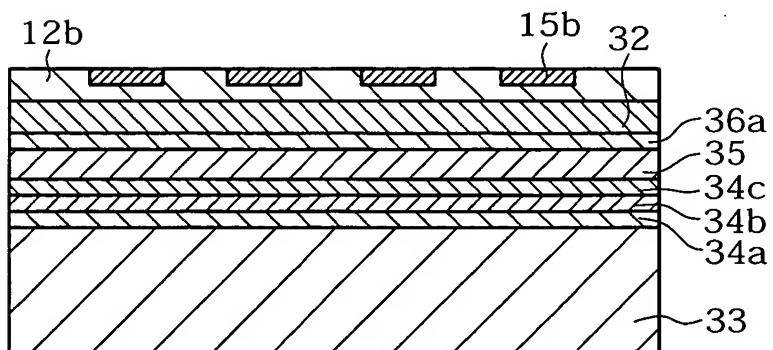
F I G . 2 1 C



F I G . 2 2 A



F I G . 2 2 B



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FIG. 23 A

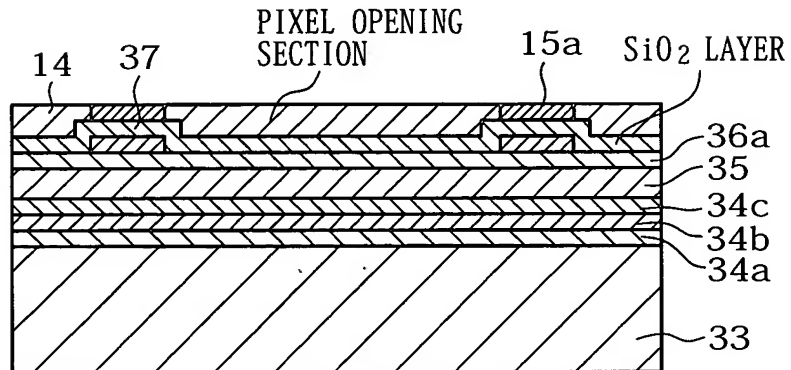


FIG. 23 B

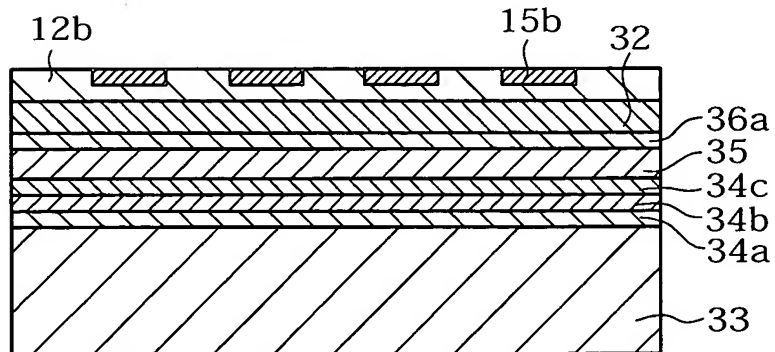


FIG. 24A

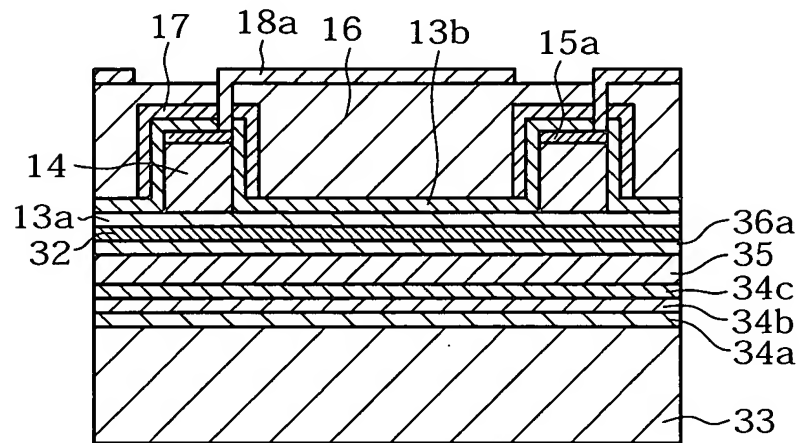
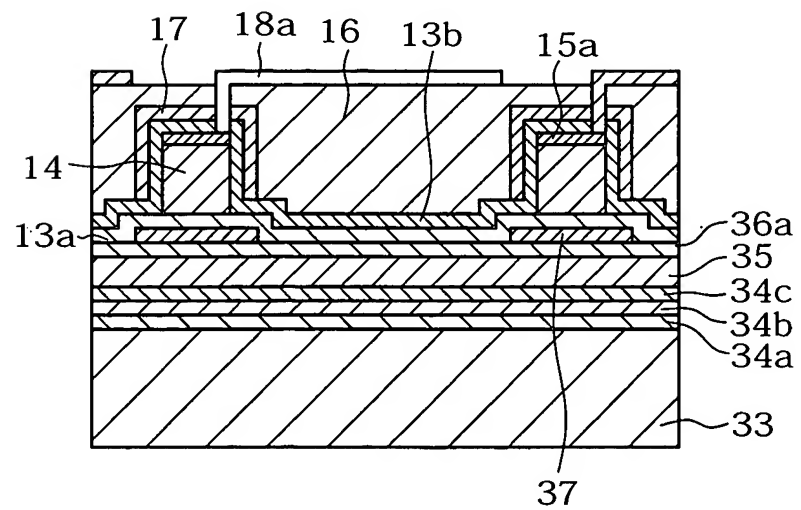


FIG. 24B



F I G. 2 5

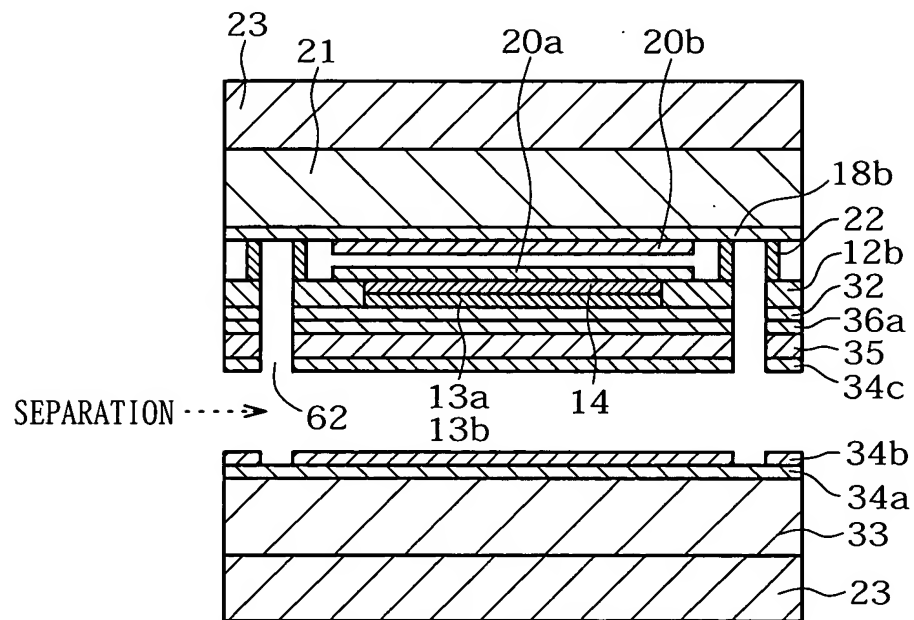


FIG. 26A

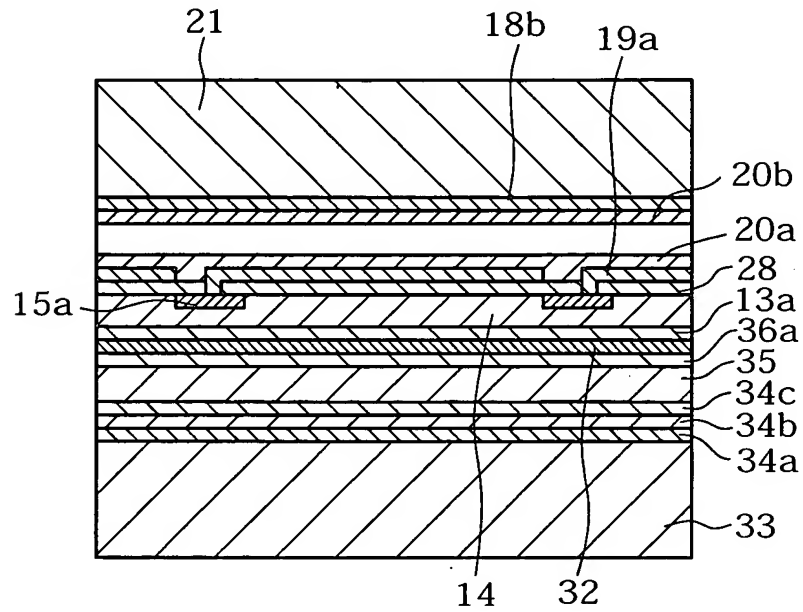
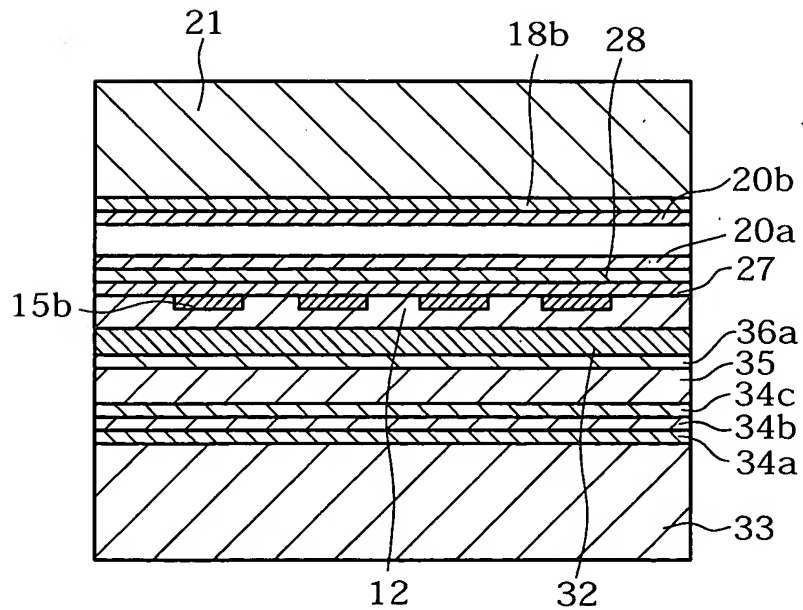
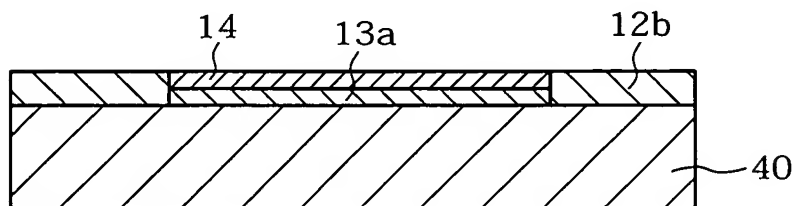


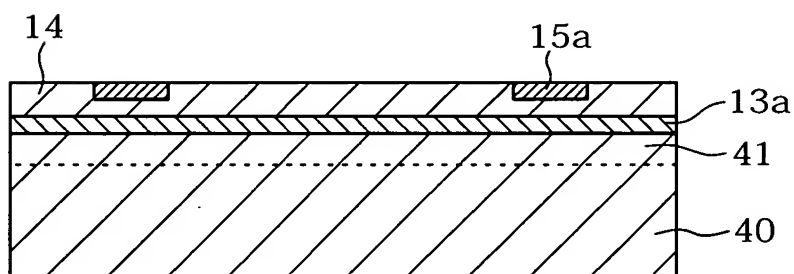
FIG. 26B



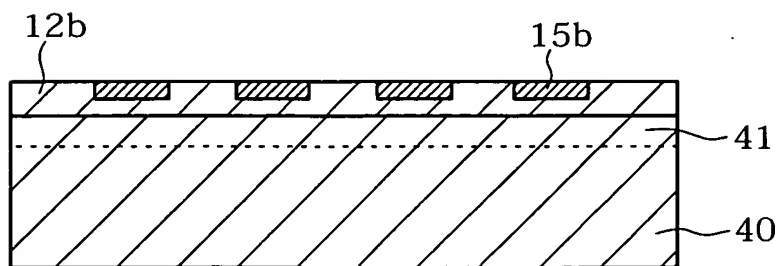
F I G . 2 7



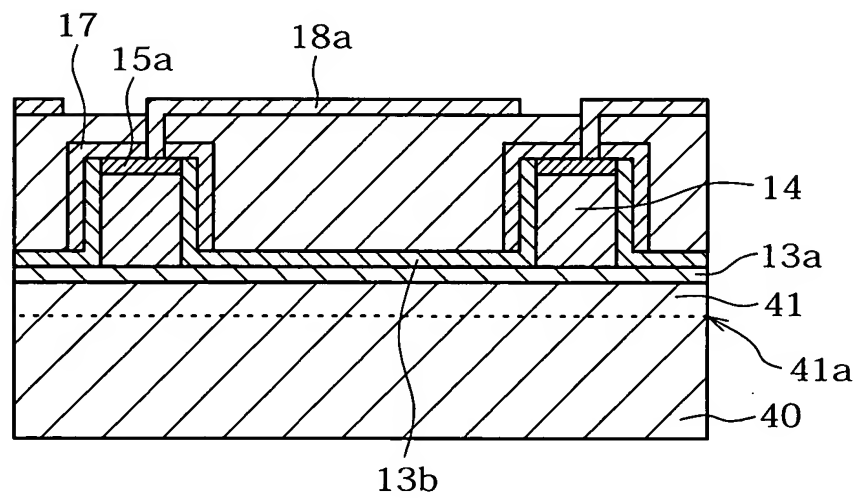
F I G . 2 8 A



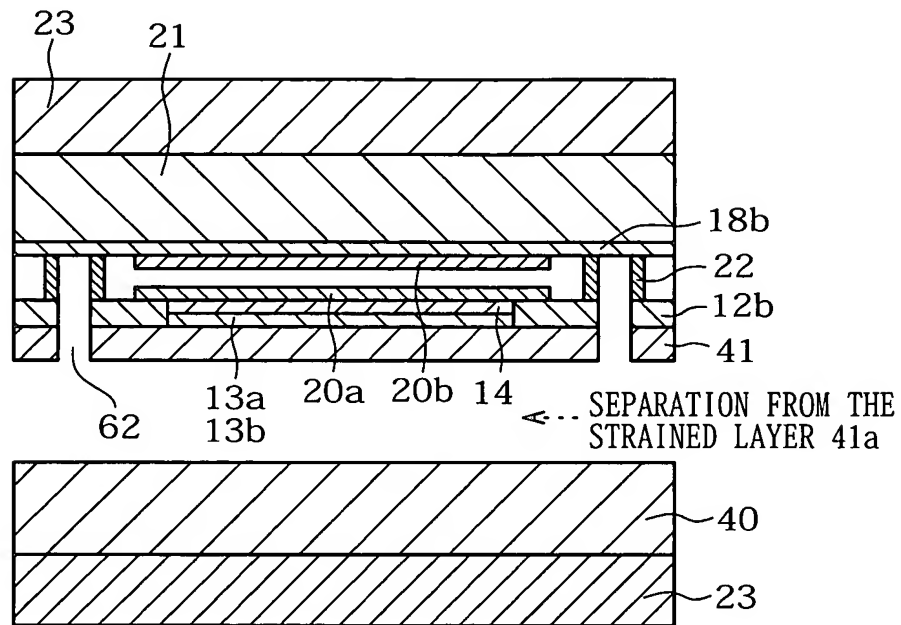
F I G . 2 8 B



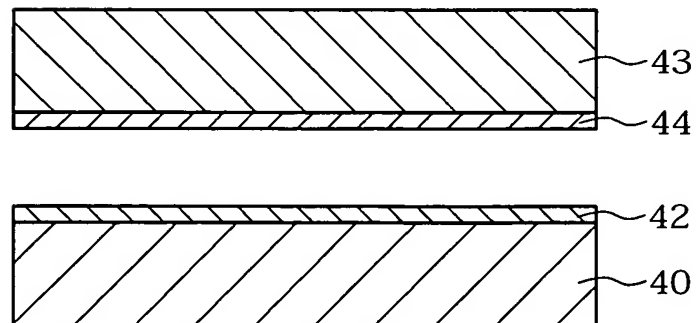
F I G . 2 9



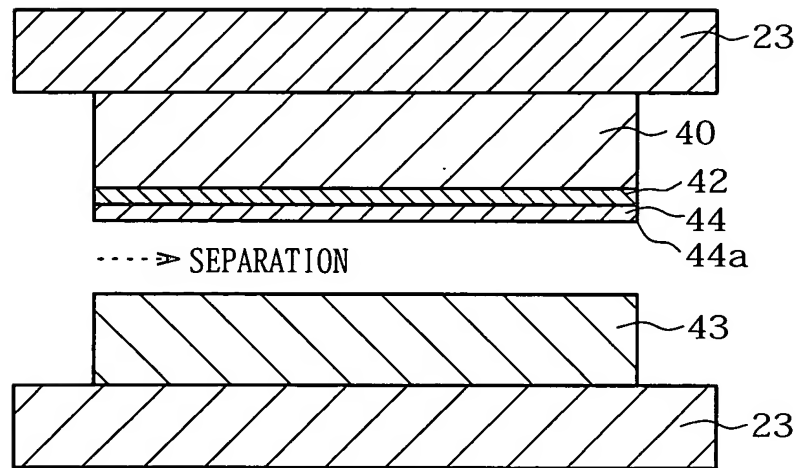
F I G. 3 0



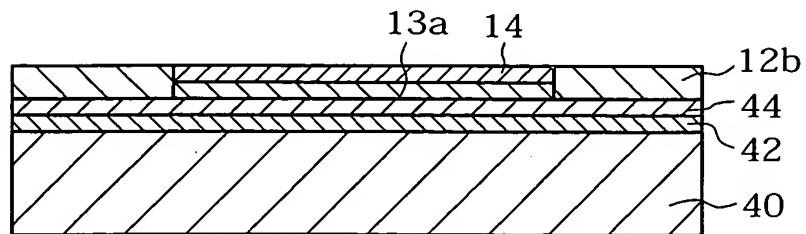
F I G. 3 1



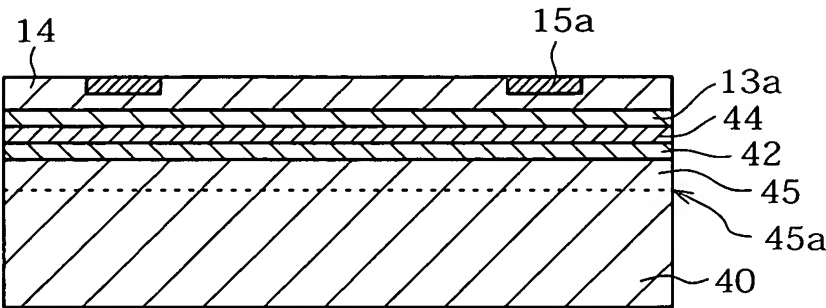
F I G . 3 2



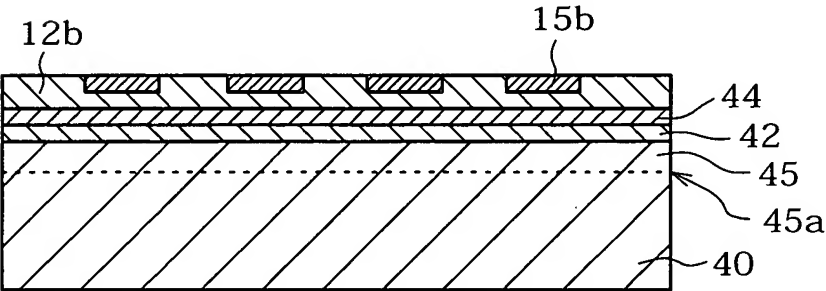
F I G . 3 3



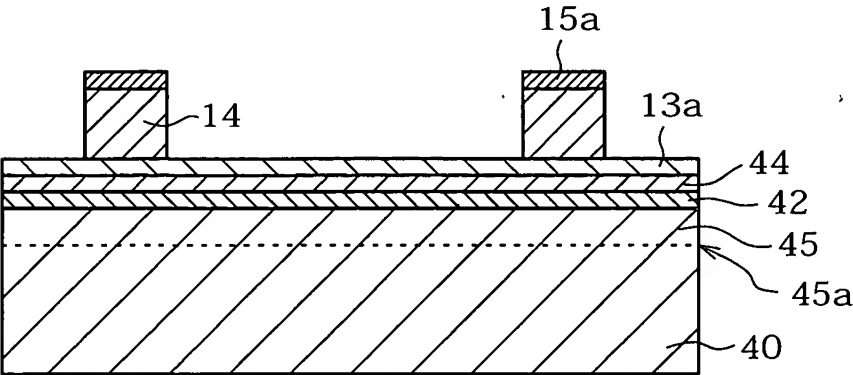
F I G . 3 4 A



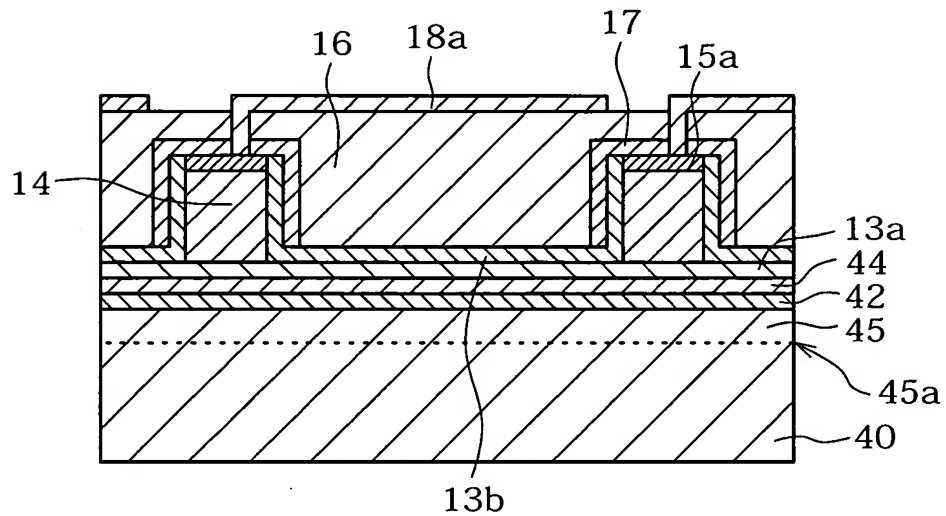
F I G . 3 4 B



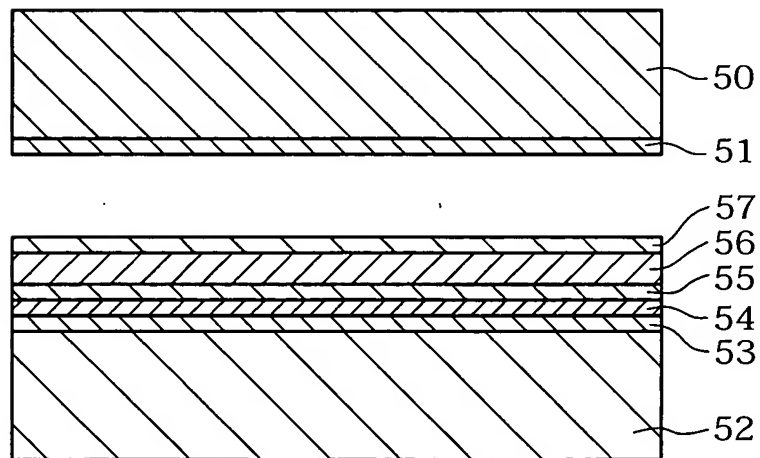
F I G . 3 5



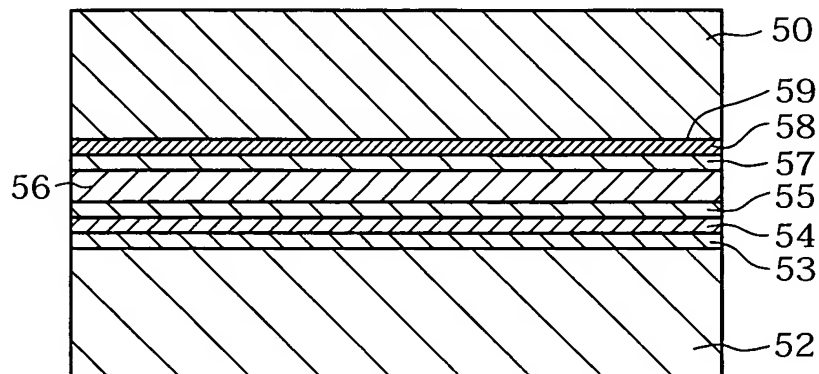
F I G . 3 6



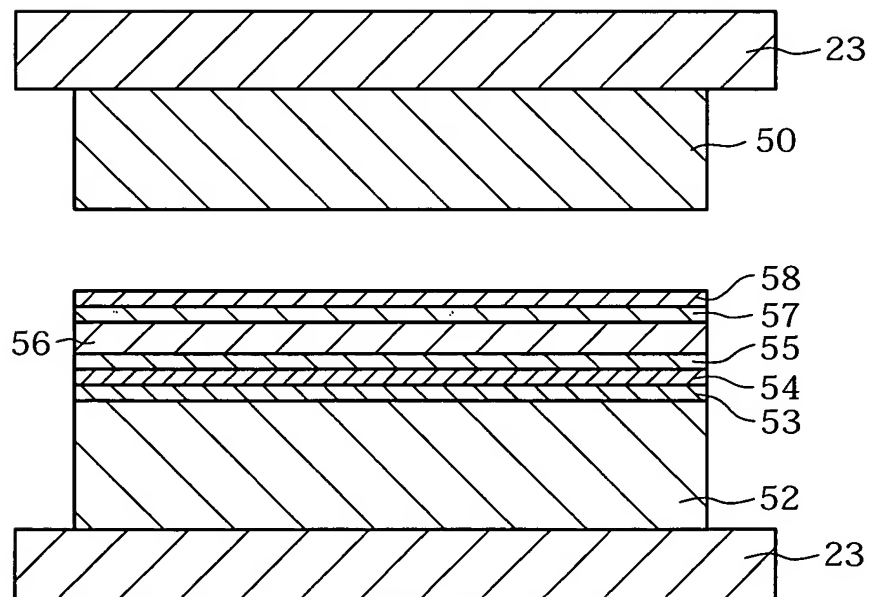
F I G . 3 7



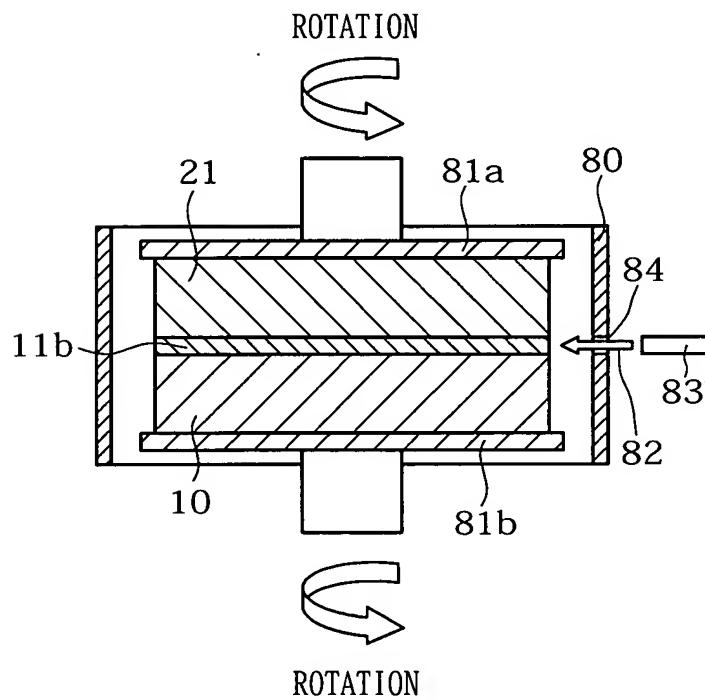
F I G . 3 8



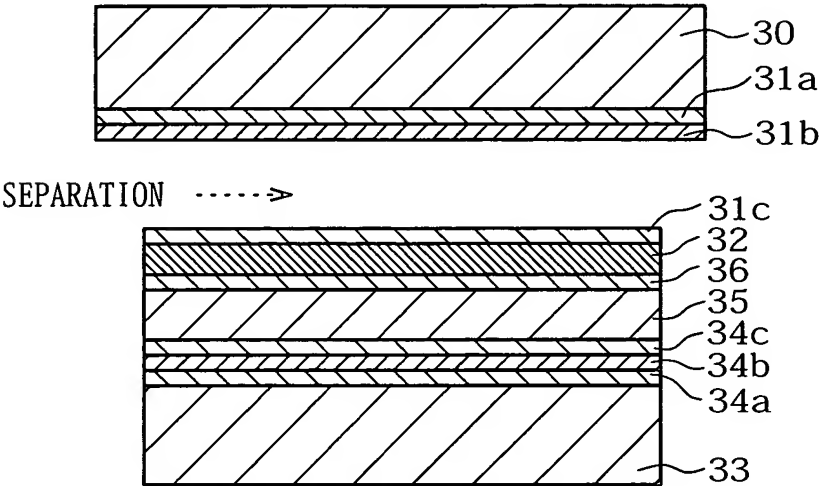
F I G . 3 9



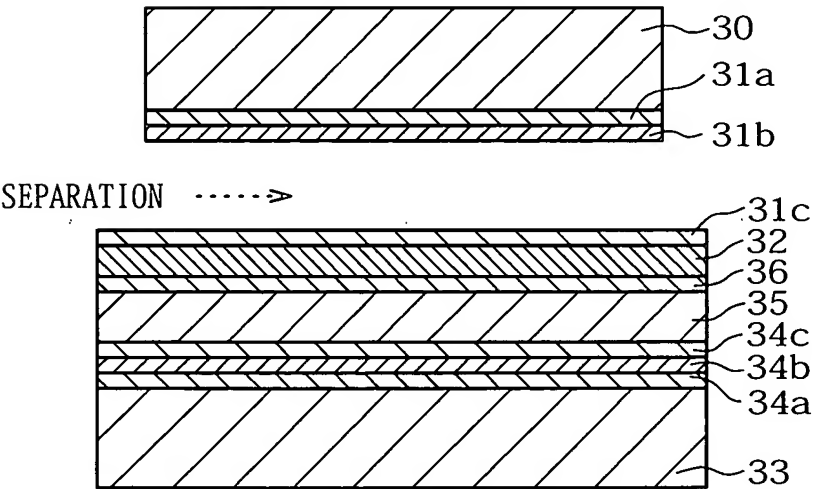
F I G . 4 0



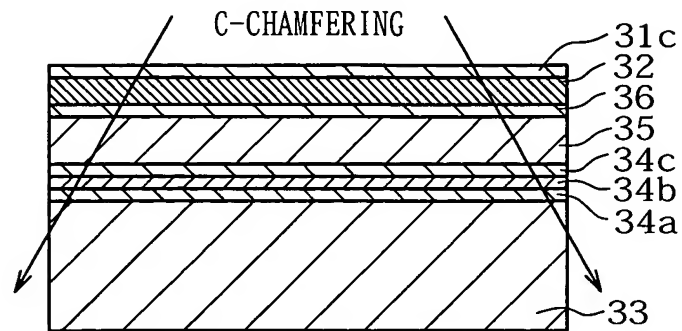
F I G . 4 1 A



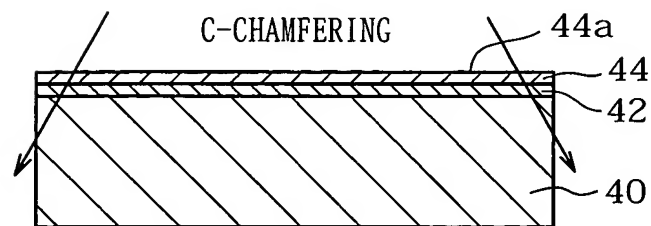
F I G . 4 1 B



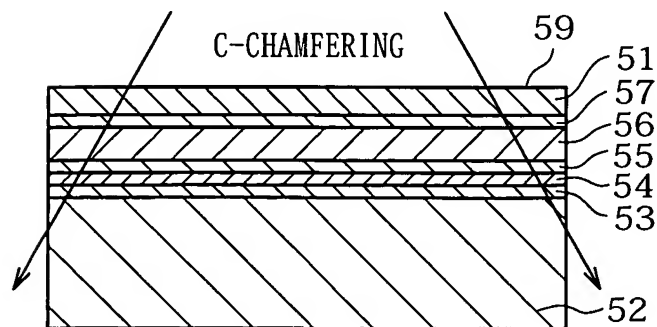
F I G . 4 2 A



F I G . 4 2 B



F I G . 4 2 C



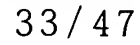


FIG. 44A

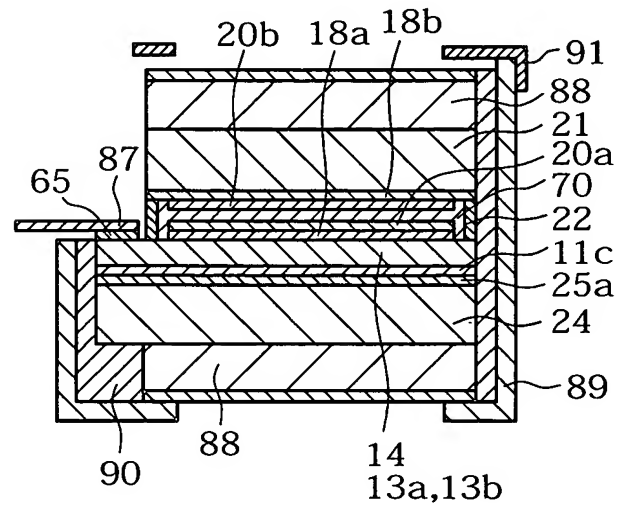


FIG. 44B

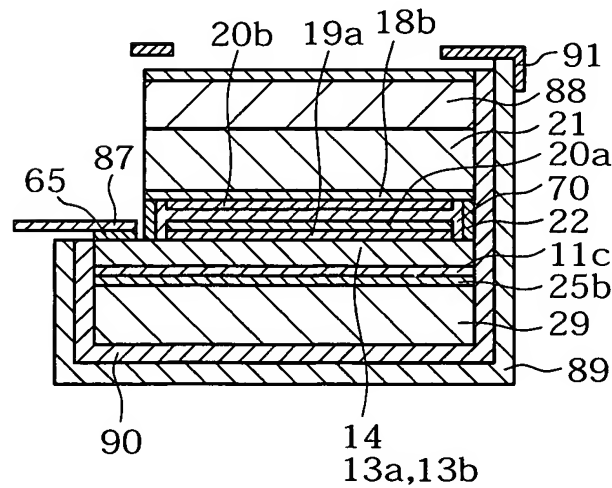


FIG. 45A

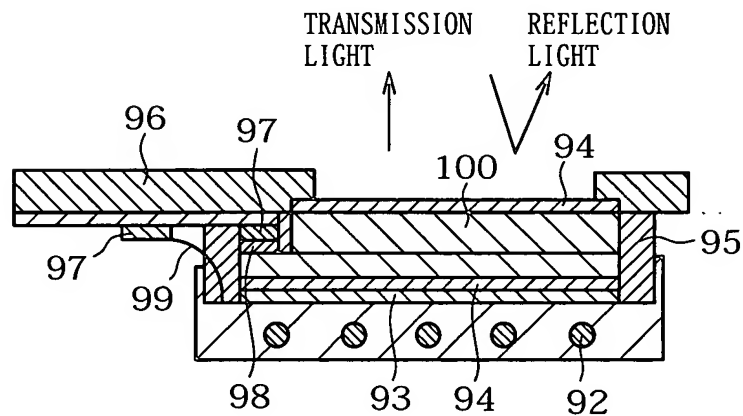
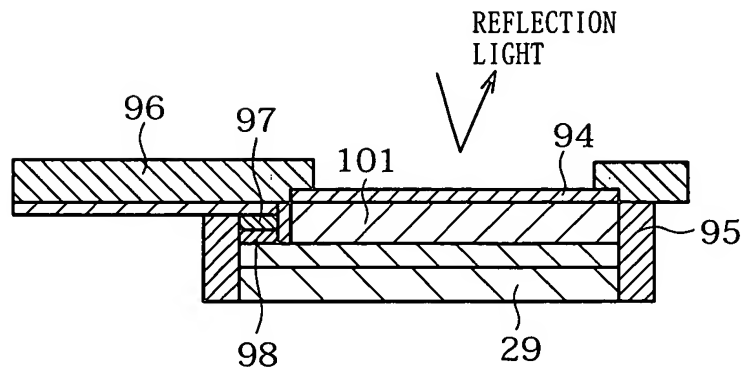
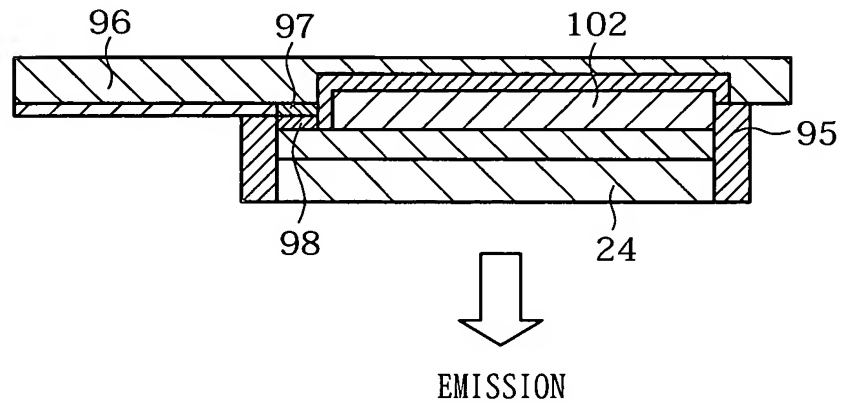


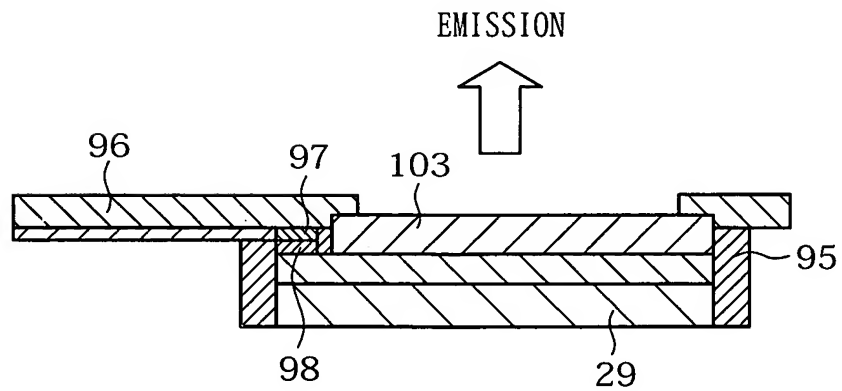
FIG. 45B



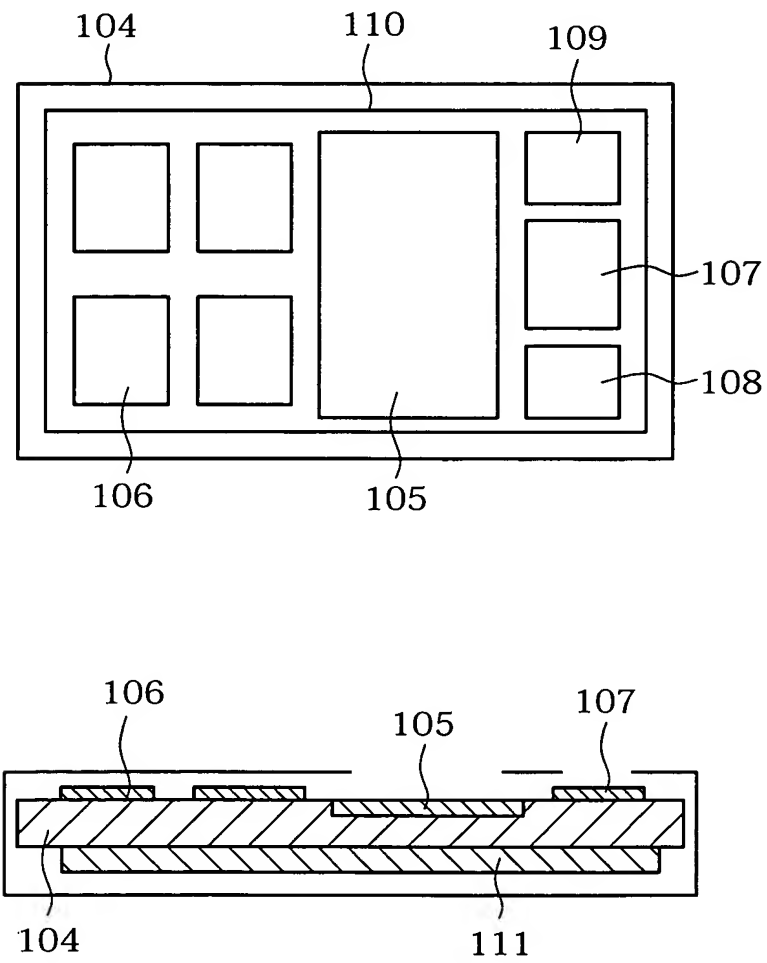
F I G . 4 6 A



F I G . 4 6 B



F I G . 4 7



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FIG. 48A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE/	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

FIG. 48B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
			FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
			FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING/TRANSPARENT SUPPORT
			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
			FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL			FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
			FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER

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FIG. 49A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY ↑	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY ↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY ↑	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY ↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE/	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

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FIG. 49B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER

FIG. 50A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE ASSEMBLY	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY ↑	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY ↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY ↑	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY ↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE /	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

FIG. 50B

SEMI-TRANSMISSIVE LCD	↑	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	↑	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT
	↑	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT	-
LOWER FACE EMISSION TYPE ORGANIC EL	-	NONE	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL SUBSTRATE LAYER
	-	YES	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL SUBSTRATE LAYER

MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

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Docket No. 075834.00466

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FIG. 51A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE ASSEMBLY	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY ↑	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY ↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY ↑	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY ↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE /	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

FIG. 51B

SEMI- TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING/TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE

FIG. 52A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE/	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

FIG. 52B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING/TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	-	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	-	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	-	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER